

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 06/13/2022

Details for "UA78M05CDCYRG3"

**Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
UA78M05CDCYRG3	SN	Level-2-260C-1 YEAR	Ext-Mfg	DCY   4	6.5x3.5x1.6	133

\*Total Device Mass  
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

**Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

**Component Information**

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Copper and Its Alloys	Copper	7440-50-8	0.096957	99.992781	999928	0.072894	729
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.001031	10	0.000001	0
Nickel and Its Alloys	Nickel	7440-02-0	0.000001	0.001031	10	0.000001	0
Other Nonferrous Metals and Alloys	Manganese	7439-96-5	0.000001	0.001031	10	0.000001	0
Precious Metals	Silver	7440-22-4	0.000004	0.004125	41	0.000003	0
Sub-Total			0.096964	100	1000000	0.072899	729
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	0.337212	76.299903	762999	0.253522	2535
Thermoplastics	Epoxy	85954-11-6	0.104744	23.700097	237001	0.078748	787
Sub-Total			0.441956	100	1000000	0.332271	3323
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	75.97275	99.799999	998000	57.117723	571177
Copper and Its Alloys	Iron	7439-89-6	0.114188	0.150001	1500	0.085849	858
Copper and Its Alloys	Phosphorus	7723-14-0	0.022838	0.030001	300	0.01717	172
Precious Metals	Silver	7440-22-4	0.015225	0.02	200	0.011446	114
Sub-Total			76.125001	100	1000000	57.232188	572322
<b>Lead Frame Plating</b>							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.914	100	1000000	0.687162	6872
Sub-Total			0.914	100	1000000	0.687162	6872
<b>Mold Compound</b>							
Other Inorganic Materials	Aluminum Nitride	24304-00-5	0.091488	0.170001	1700	0.068782	688
Other Inorganic Materials	Fused Silica	60676-86-0	48.100978	89.379997	893800	36.163207	361632
Other Nonferrous Metals and Alloys	Antimony Trioxide	1309-64-4	0.048435	0.090001	900	0.036414	364
Other Organic Materials	Brominated Epoxy	40039-93-8	0.048435	0.090001	900	0.036414	364
Other Plastics and Rubber	Carbon Black	1333-86-4	0.118396	0.22	2200	0.089012	890
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.764191	1.42	14200	0.574533	5745
Thermoplastics	Epoxy	85954-11-6	4.644344	8.63	86300	3.491704	34917
Sub-Total			53.816267	100	1000000	40.460068	404601
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	1.61663	100	1000000	1.215412	12154
Sub-Total			1.61663	100	1000000	1.215412	12154
<b>Total</b>			133.010818			100	1000000

**Important Note**  
 The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.  
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.  
[See Glossary of Terms for more details.](#)

**Important Part Information**  
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

**Product Content Methodology**  
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

**Material Declaration Certificate for Semiconductor IC Packaged Products**

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

**Important Information/Disclaimer**  
 TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."  
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality  
 For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
 Created on: 06/13/2022

**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meets JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.